WAFER TRANSFER BLADE

Abstract

Projections 22 of the blade 16 provided on a blade surface in a wafer-loading region 18b of a body 18 support a wafer W loaded on the blade surface 18a. Since the projections 22 have microgrooves formed by surface roughening, the wafer W is retained on the projections 22 with a suppressed displacement. The blade 16 has a simple structure that retains the wafer W without vacuum suction and has no receiving hole to retain the wafer W in the body 18 of the blade 16. This can effectively prevent formation of defects on the wafer W.

(Fig. 1)